

Thermal Pad XK-P20/P20S

Introduction

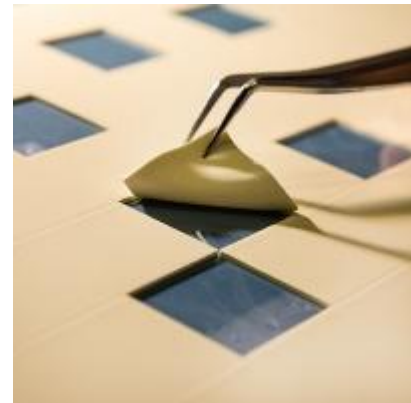
This series of products are resilient and with large deformation, suitable for large institutional design tolerances. Single or Double layer structure, The Double layer is reinforced with special ultra-thin fabric to increase resistance and workability of punching, strip type, Malformation designs. Self-adhesive and never recede. No corrosion to the Copper surface, "environmentally friendly products" .

Features

Ultra conformable, "gel-like" modulus
Designed for low-stress applications
low hardness

Applications

Telecommunications
Computer, Between heat-generating semiconductor and a heat sink



	Unit	XK-P20					XK-P20S	Method
Reinforcement Carrier		-	-	-	-	-	Fiberglass	-
Inherent Surface Tack	1/2 Sided	2-side	2-side	2-side	2-side	2-side	2-side	-
Color	-	Pink	Pink	Pink	Pink	Pink	Pink	Visual
Thickness	mm	0.3~5.0	0.3~5.0	0.3~5.0	0.3~5.0	0.3~5.0	0.3~5.0	ASTM D 374
Specific Gravity	g/cm ³ ,±0.05	2.55	2.75	2.90	3.10	3.1	2.90	ASTM D 792
Hardness	Shore 00	40~55	40~55	40~55	50~65	55-70	50~65	ASTM D 2240
Thermal Impedance @0.5mm 14.5psi	°C.in ² /W	≤0.95	≤0.85	≤0.70	≤0.55	≤0.20	≤0.79	ASTM D 5470
Thermal Conductivity	W/(m.K)	≥1.2	≥1.5	≥2.0	≥2.5	≥3.0	≥2.0	HOT DISK
Volume Resistivity	Ω.cm	≥10 ¹³	≥10 ¹³	≥10 ¹³	≥10 ¹³	≥10 ¹³	≥10 ¹³	ASTM D 257
Breakdown Voltage	kV/mm	≥10	≥10	≥10	≥10	≥10	≥10	ASTM D 149
Dielectric Constant	±1.0	5.5	6.5	6.5	6.5	7	7.5	ASTM D 150
Application Temperature	°C	-50~200	-50~200	-50~200	-50~200	-50~200	-50~200	DSC,UL 746B
Tensile Strength	Psi	≥18	≥15	≥15	≥15	≥15	≥100	ASTM D 638
Elongation	%	≥100	≥100	≥80	≥50	≥40	≥20	ASTM D 638
Siloxane Volatiles D4~D20	w,%	<0.01	<0.01	<0.01	<0.01	<0.01	<0.01	GC-FID
Flammability	Vertical	V-0	V-0	V-0	V-0	V-0	V-0	UL 94